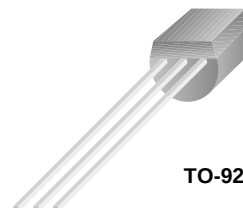


BF494

NPN RF Transistor



TO-92

1. Collector 2. Emitter 3. Base

Absolute Maximum Ratings * $T_a = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_{CEO}	Collector-Emitter Voltage	20	V
V_{CBO}	Collector-Base Voltage	30	V
V_{EBO}	Emitter-Base Voltage	5.0	V
I_C	Collector Current - Continuous	30	mA
T_J	Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	- 55 ~ 150	$^\circ\text{C}$

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

Thermal Characteristics

Symbol	Parameter	Value	Unit
P_D	Total Device Dissipation, by $R_{\theta JA}$ Derate above 25°C	350 2.8	mW mW/ $^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to case	125	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	$^\circ\text{C/W}$

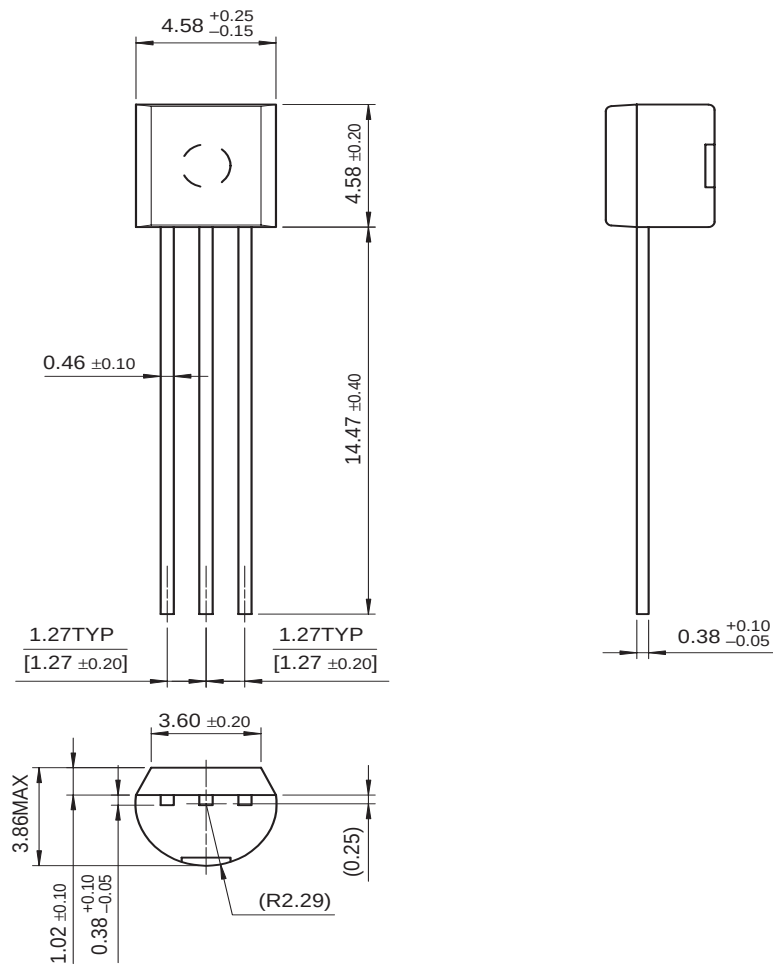
Electrical Characteristics* $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max.	Units
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1.0\text{mA}$, $I_B = 0$	20		V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 10\mu\text{A}$, $I_E = 0$	30		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10\mu\text{A}$, $I_C = 0$	5.0		V
I_{CES}	Collector-Emitter Sustaining Current	$V_{CE} = 40\text{V}$, $V_{EB} = 0\text{V}$		10	nA
h_{FE}	DC Current Gain	$V_{CE} = 10\text{V}$, $I_C = 1\text{mA}$	67	222	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 10\text{mA}$, $I_B = 5\text{mA}$		0.2	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 10\text{mA}$, $I_B = 5\text{mA}$		0.92	V
$V_{BE(ON)}$	Base-Emitter On Voltage	$V_{CE} = 10\text{V}$, $I_C = 10\text{mA}$	650	740	mV

* DC Item are tested by Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Package Dimensions

TO-92



Dimensions in Millimeters

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Definition of Terms

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